

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Cancelled)

2. (Currently Amended) A semiconductor device, comprising:

a rectangle-shaped lower carrier substrate;

an upper carrier substrate mounted on the lower carrier-substrate;

a semiconductor chip mounted on the upper carrier substrate;

wherein the lower carrier substrate includes:

a region without a protruding electrode that is provided along at least two sides which intersect at a first vertex of the upper carrier substrate; and

a protruding electrode group which is provided along at least two sides which intersect at a second vertex of the upper carrier substrate opposite the first vertex.

3. (Currently Amended) A semiconductor device, comprising:

a rectangle-shaped lower carrier substrate;

an upper carrier substrate mounted on the lower carrier substrate;

a semiconductor chip mounted on the upper carrier substrate;

wherein the lower carrier substrate includes:

a region without a protruding electrode which is provided along at least a first side of the upper carrier substrate; and

a protruding electrode group which is provided along a second side of the upper carrier substrate opposite the first side, and along at least a third side which intersects the second side.

4. (Original) The semiconductor device according to claim 3, wherein the protruding electrode group is arranged in a U-shape.

5. (Currently Amended) A semiconductor device, comprising:
a lower carrier substrate;
a plurality of upper carrier substrates mounted on the lower carrier substrate,
each of the upper carrier substrates including a plurality of semiconductor chips stacked
thereon; and

a protruding electrode group arranged on the lower carrier substrate, the
protruding electrode group excluded from a region where a semiconductor chip is
mounted on the lower carrier substrate so as to be arranged to be overlapped by an
ends of the upper carrier substrates.

6. (Currently Amended) A semiconductor device, comprising:
a lower carrier substrate;

a plurality of upper carrier substrates mounted on the lower carrier substrate,
each of the upper carrier substrates including a plurality of semiconductor chips stacked
thereon;

a semiconductor chip mounted on the lower carrier substrate;

a plurality of land electrodes formed on the lower carrier substrate; and

a protruding electrode arranged on a part of each of the plurality of land electrodes,

wherein the upper carrier substrates are supported by the protruding electrodes
such that an end of each of the upper carrier substrates overlap the semiconductor chip
mounted on the lower carrier substrate.

7. (Original) A semiconductor device, comprising:

a first carrier substrate;

a first semiconductor chip mounted on the first carrier substrate;

a rectangle-shaped second carrier substrate;

a second semiconductor chip mounted on the second carrier substrate;

a region without a protruding electrode that is provided along at least two sides which intersect at a first vertex of the second carrier substrate; and

a protruding electrode group which is provided along at least two sides which intersect at a second vertex of the second carrier substrate opposite the first vertex, and which is bonded to the first carrier substrate so as to arrange the first semiconductor chip under the region without a protruding electrode.

8. (Original) A semiconductor device, comprising:

a first carrier substrate;

a first semiconductor chip mounted on the first carrier substrate;

a rectangle-shaped second carrier substrate;

a second semiconductor chip mounted on the second carrier substrate;

a region without a protruding electrode which is provided along at least a first side of the second carrier substrate; and

a protruding electrode group which is provided along a second side of the second carrier substrate opposite the first side, and along at least a third side which intersects the second side, and which is bonded to the first carrier substrate so as to arrange the first semiconductor chip under the region without a protruding electrode.

9. (Cancelled)

10. (Cancelled)

11. (Original) An electronic device, comprising:

a first carrier substrate;

a first electronic component mounted on the first carrier substrate;

a rectangle-shaped second carrier substrate;

a second electronic component mounted on the second carrier substrate;

a region without a protruding electrode that is provided along at least two sides which intersect at a first vertex of the second carrier substrate; and

a protruding electrode group which is provided along at least two sides which intersect at a second vertex of the second carrier substrate opposite the first vertex, and which is bonded to the first carrier substrate so as to arrange the first electrode component under the region without a protruding electrode.

12. (Original) An electronic device, comprising:

- a first carrier substrate;
- a first electronic component mounted on the first carrier substrate;
- a rectangle-shaped second carrier substrate;
- a second electronic component mounted on the second carrier substrate;
- a region without a protruding electrode which is provided along at least a first side of the second carrier substrate; and
- a protruding electrode group which is provided along a second side of the second carrier substrate opposite the first side, and along at least a third side which intersects the second side, and which is bonded to the first carrier substrate so as to arrange the first electronic component under the region without a protruding electrode.

13. (Original) Electronic equipment, comprising:

- a first carrier substrate;
- a first semiconductor chip mounted on the first carrier substrate;
- a rectangle-shaped second carrier substrate;
- a second semiconductor chip mounted on the second carrier substrate;

a region without a protruding electrode that is provided along at least two sides which intersect at a first vertex of the second carrier substrate;

a protruding electrode group which is provided along at least two sides which intersect at a second vertex of the second carrier substrate opposite the first vertex, and which is bonded to the first carrier substrate so as to arrange the first semiconductor chip under the region without a protruding electrode; and

a motherboard where the first carrier substrate is mounted.

14. (Original) Electronic equipment, comprising:

a first carrier substrate;

a first semiconductor chip mounted on the first carrier substrate;

a rectangle-shaped second carrier substrate;

a second semiconductor chip mounted on the second carrier substrate;

a region without a protruding electrode which is provided along at least a first side of the second carrier substrate;

a protruding electrode group which is provided along a second side of the second carrier substrate opposite the first side, and along at least a third side which intersects the second side, and which is bonded to the first carrier substrate so as to arrange the first semiconductor chip under the region without a protruding electrode; and

a motherboard where the first carrier substrate is mounted.

15. (Cancelled)

16. (Cancelled)

17. (New) The semiconductor device according to claim 2, further comprising:

a plurality of upper carrier substrates mounted on the lower carrier substrate; and

a plurality of semiconductor chips stacked on each of the upper carrier substrates.

18. (New) The semiconductor device according to claim 3, further comprising:

a plurality of upper carrier substrates mounted on the lower carrier substrate; and

a plurality of semiconductor chips stacked on each of the upper carrier substrates.